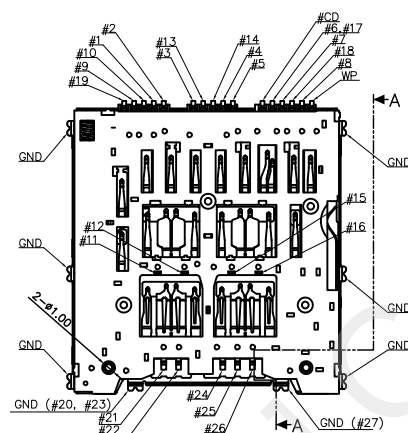
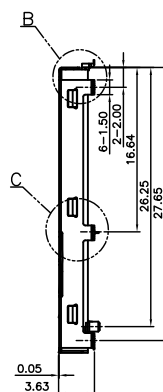
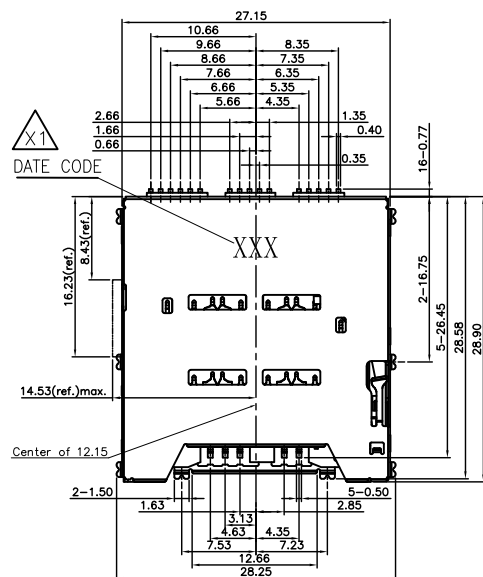
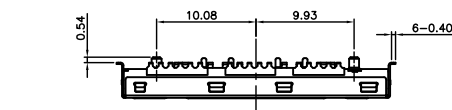




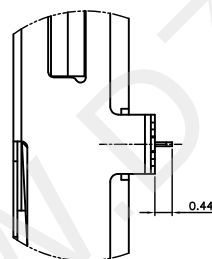
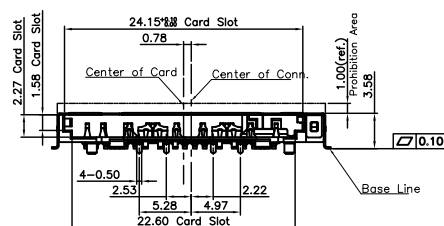
Section A-A

Date Code: 0 C Q

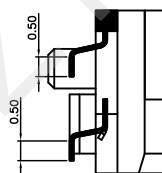

(制程喷码依最新生产日期)

NOTE:

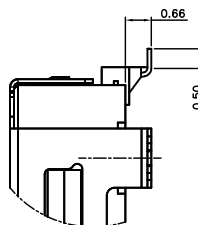
1. Material:
 - 1-1 Housing:LCP 475, Color Black UL94-V0
 - 1-2 Contact: Phosphor Bronze
 - 1-3 Cover: SUS304-H
- 2.Plating:
 - 2-1 Contact terminal:
Contact area: Gold 5u" Min.
Underplating: Ni overall 50U" Min. Solder area: Gold 5u" Min .
 - 2-2 Cover:
Underplating: Solder Ni overall 50U" Min.
3. Specification:
 - 3-1.Current Rating :0.5A max.
 - 3-2.Contact Resistance: 50 mOhms max
 - 3-3.Insulation Resistance:1000 MOhms min./500VDC
 - 3-4.Dielectric Withstanding Voltage:500 V AC/1minute
 - 3-5.Operating Temperature:-25°C to+85°C
 - 3-6.Insertion force: 9.8N Max
 - 3-7.Extraction force: 9.8N Max
 - 3-8.Durability:10000 Cycles
4. Product Compliant to HalogenFree+ RoHS2 Directive 2002/95/EC and ELV 2000/53/EC
5. Recommending A Metal More Than 0.15mm Thick.
Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.



Detail C
Scale 4 : 1



Detail D
Scale 4 : 1

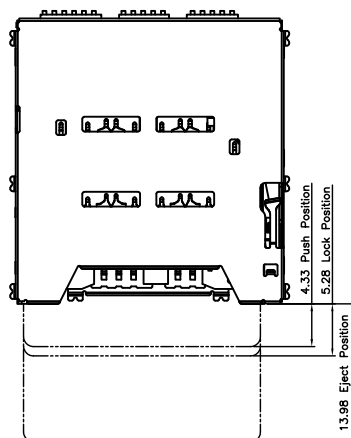


Detail B
Scale 4 : 1

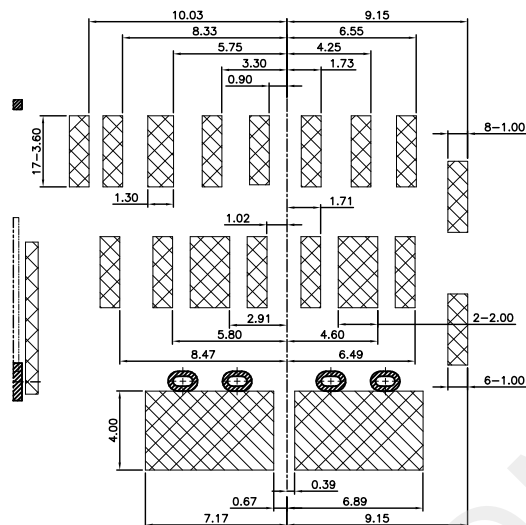
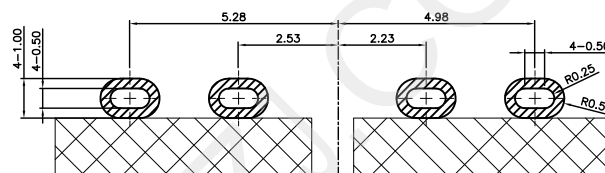


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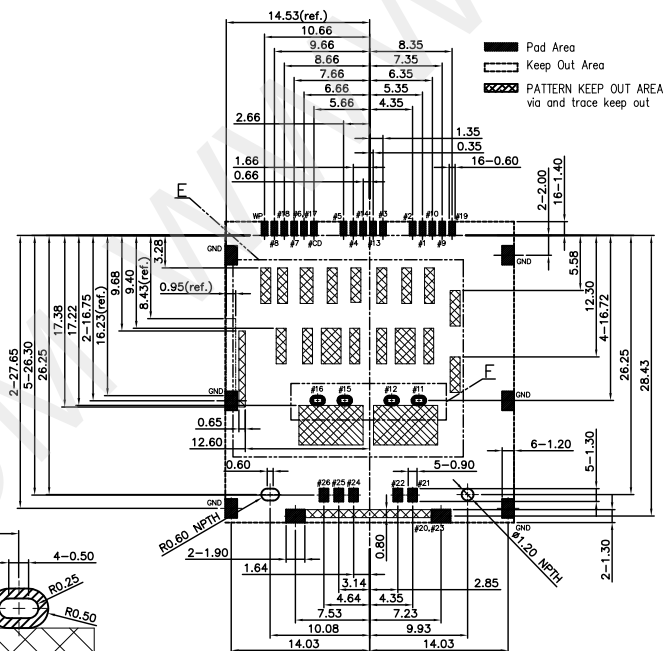
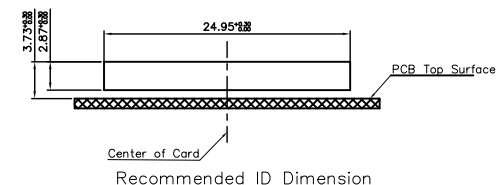
TOLERANCE:		DRAWN BY :		DATE :		PART NAME:	
X.X ±0.30		陈一鸣		2014-02-23		SD 8.0 PUSH SMT 3.58H	
X.XX ±0.25		CHECKED BY:		DATE :		PART NO.	
X.XXX ±0.15						HYC99-SD29-358	
X: ±2° X.X ±0.5°		马跃		2014-02-23		MOLD NO.	
						DRAW NO:	
		HYC-2509011549					
UNIT: mm [inch]		APPROVED BY:		DATE :		SHEET NO.	
SCALE:1:1 SIZE: A4		邱敏		2014-02-23		1 OF 1	



No.	PIN No	FUNCTION		
		SD Mode	UHS-II Mode	PCIe Mode
No.1	#1	CD/DAT3	—	PERST#
No.2	#2	CMD	—	—
No.3	#3	VSS1	VSS1	VSS1
No.4	#4	VDD	VDD1	VDD1
No.5	#5	CLK	—	—
No.6	#6	VSS2	VSS2	VSS2
No.7	#7	DAT0	RCLK+	REFCLK+
No.8	#8	DAT1	RCLK-	REFCLK-
No.9	#9	DAT2	—	CLKREQ#
No.10	#10	—	VSS3	VSS3
No.11	#11	—	D0+	PCIe_Tx0+
No.12	#12	—	D0-	PCIe_Tx0-
No.13	#13	—	VSS4	VSS4
No.14	#14	—	VDD2	VDD2
No.15	#15	—	D1-	PCIe_Rx0-
No.16	#16	—	D1+	PCIe_Rx0+
No.17	#17	—	VSS5	VSS5
No.18	#18	—	VDD3	VDD3
No.19	#19	—	VDD1a	VDD1a
No.20	#20	—	VSS6	VSS6
No.21	#21	—	PCIe_Tx1+	PCIe_Tx1+
No.22	#22	—	PCIe_Tx1-	PCIe_Tx1-
No.23	#23	—	VSS7	VSS7
No.24	#24	—	VDD2a	VDD2a
No.25	#25	—	PCIe_Rx1-	PCIe_Rx1-
No.26	#26	—	PCIe_Rx1+	PCIe_Rx1+
No.27	#27	—	VSS8	VSS8
No.28	#CD	CARD DETECT		
No.29	#WP	WRITE PROTECT		

Detail E
Scale 2 : 1Detail F
Scale 4 : 1

Card Uninsertion	
Card Write Protect insertion	
Card Normal insertion	

RECOMMEND P.C.B LAYOUT(TOP VIEW)
(Tolerances Unless Otherwise Spec. ±0.05)

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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.* ±2" X.X* ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: SD 8.0 PUSH SMT 3.58H
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC99-SD29-358
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2509011549
			SHEET NO. 1 OF 1